



Material Content Data Sheet



Sales Product Name		BTS7080-2EPA		Issued		1. August 2018			
MA#		MA001673670							
Package		PG-TSDSO-14-22		Weight*		64.87 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.954	1.47	1.47	14709	14709	
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		145		
	non noble metal	zinc	7440-66-6	0.038	0.06		581		
	non noble metal	iron	7439-89-6	0.754	1.16		11624		
wire	non noble metal	copper	7440-50-8	30.617	47.21	48.44	471998	484348	
	non noble metal	copper	7440-50-8	0.387	0.60	0.60	5966	5966	
	encapsulation	organic material	carbon black	1333-86-4	0.088	0.14		1355	
plating	plastics	epoxy resin	-	3.428	5.28		52848		
	inorganic material	silicondioxide	60676-86-0	25.784	39.75	45.17	397491	451694	
	leadfinish	non noble metal	tin	7440-31-5	1.642	2.53	2.53	25308	25308
glue	noble metal	silver	7440-22-4	0.816	1.26	1.26	12581	12581	
*deviation	< 10%	plastics	epoxy resin	-	0.061	0.09		944	
		noble metal	silver	7440-22-4	0.289	0.44	0.53	4450	5394
Sum in total:						100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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